

High spatial resolution pad and pixelated TPC technology R&D

Huirong Qi

Yue Chang, Liwen Yu, Xin She, Jian Zhang , Zhiyang Yuan, Hongliang Dai, Jinxian Zhang Linghui Wu, Gang Li, Manqi Ruan and some good inputs from LCTPC

CEPC Day, 19 December, 2022

- **TPC detector for e+e- colliders**
- High spatial resolution pad readout TPC
- Pixelated readout TPC R&D
- Summary

TPC technology for the future e+e- colliders

- A TPC is the main tracking detector for **some candidate experiments at future e+e- colliders**
 - ILD at ILC and the baseline detector concept of CEPC
- TPC technology can be of interest for other future e+e- colliders



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TPC requiremetns from e+e- Higgs/EW/Top factories

- TPC can provide hundreds of hits (for track finding) with high spatial resolution compatible with PFA design (very low material in chamber)
 - $\sigma_{1/pt} \sim 10^{-4}$ (GeV/c)⁻¹ with TPC alone and $\sigma_{point} < 100 \mu m$ in r ϕ
- **Provide dE/dx and dN/dx with a resolution** <4%
 - Essential for Flavor physics @ Z run
 - Beneficial for jet at higher energy





Pad and pixelated readout TPC technology

- TPC as the main tracker detector to satisfy the physics requirements :
 - For Higgs, W and top running, **no problem** for all TPC readout technologies.
- For high luminosity (2×10^{36}) Z running
 - Pixelated readout TPC is a good option at **high luminosity** on the circular e+e- collider
 - Pixelated readout TPC is a realistic option to provide
 - High spatial resolution under 2T or 3T magnetic field
 - Better momentum resolution
 - High-rate operation (MHz/cm²)
 - dE/dx and Cluster counting (in space)
 - Excellent two tracks separation

Standard charge collection:

Pads (1 mm \times 6 mm)/ long strips

Pixelated readout:

Bump bond pads are used as charge collection pads. $55 \mu m \times$ 55 μm or larger



• High spatial resolution pad TPC technology

Pad TPC technology - double GEMs

- GEMs: copper-insulator- copper sandwich with holes
- Double GEMs module are being tested:
 - GEMs with 100µm LCP insulator
 - Standard GEM from CERN
- Design idea of the GEM Module:
 - **No frame** at modules both sides

GEM Module 1:

- 2 GEMs made of 100 µm thick LCP
- 1.2×5.4mm² pads

• Spatial resolution of $\sigma_{r\phi} \leq 100 \ \mu m$, more stability by the broader arcs at top and bottom



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Pad TPC technology - triple GEMs

- Design idea of GEM Module 2:
 - Minimize dead area
 - Without frame to stretch GEMs, but a 1 mm grid to hold GEM
- Spatial resolution of σ_{rφ}≤100 µm, and double track resolution and dE/dx calculated in dependence on the pad sizes

GEM Module 2:

- 1.26 × 5.85mm2 pads staggered
- Field shaping wire on side of module to compensate the field distortions





Pad TPC technology - Resistive Micromegas

- Resistive Micromegas:
 - Bulk-Micromegas with 128 µm gap size between mesh and resistive layer (developed in LCTPC)
- A new HV scheme of the module (ERAM) places grid on ground potential
 - Reduces **field distortions** between modules by a factor of 10





https://doi.org/10.1016/j.nima.2019.162798 Huirong Oi



CEPC TPC detector prototyping roadmap

- From TPC module to TPC prototype R&D for beam test
 - Low power consumption FEE ASIC (reach <5mW/ch including ADC)
- Achievement by far:
 - Supression ions hybrid GEM+Micromegas module
 - IBF×Gain ~1 at Gain=2000 validation with GEM/MM readout
 - Spatial resolution of $\sigma_{r_0} \leq 100 \ \mu m$ by TPC prototype
 - dE/dx for PID: <4% (as expected for CEPC baseline detector concept)





Low power consumption readout

Pad TPC technology – GEM+Micromegas

- **GEM and Micromegas** groups have finished analysis of test beam data with previous set of detector modules. Both technologies show **very similar performance**.
- LCTPC want to implement improvements in a **new generation of modules** => **common modules**
 - Common readout electronics (sALTRO)
 - Only the gas amplification stage differs
- Combined Micromegas + GEM readout has been developed, which promises a **lower ion backflow** (IBF) at CEPC TPC group without gating.
 - IBF×Gain ~ 1 at total gain of 2000



TPC prototype with 266nm UV laser tracks

- The TPC prototype integrated 266nm UV laser tracks has successfully developed.
- Analysis of UV laser signal, the spatial resolution, dE/dx resolution
 - Spatial resolution can be less than 100 µm along the drift length of TPC prototype
 - Pseudo-tracks with 220 layers (same as the actual size of CEPC baseline detector concept) and dE/dx is about 3.4 \pm 0.3%



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15

10

data

 $\sigma_{\rm dE/dx} = 3.36 \pm 0.26 \,\%$

 $- \sigma_0 \cdot (N_{hits})^{-k}$

https://doi.org/10.1016/j.nima.2022.167241 Huirong Oi

Reconstruction event and energy spectrum of ⁵⁵Fe/Cosmic ray

- TPC detector prototype can study the UV laser track, 55Fe radiation source and the cosmic ray.
- TPC prototype was checked after one year development
 - ⁵⁵Fe X-ray spectrum profile is very good
 - Detector gain just shift 2% than one year before.
- The Landau distribution of the cosmic ray's energy spectrum was successfully obtained.

Summary of the event sele	ction cuts.	
Laser energy monitor	Variation range	$E_{mean} \pm \sigma$
TPC detector	Hit ToA	layer#1 2.6 ~ 2.9 μs
		layer#2 5.7 ~ 6.0 μ s
		layer#3 8.2 ~ 8.5 μs
		layer#4 10.5 ~ 11.0 μ s
	Trigger pads	≥ 2 for each column
Laser and detector	The laser control chassis triggers the energy monitor and DAQ system at the same time.	



• Pixelated TPC technology

Pixelated TPC technology – Large scale readout

- TPC prototype with GridPixes:
 - A module **with 32 GridPixes has been constructed** and was in a test beam in B=1.0T at DESY in June 2021.
 - Very high detection efficiency results in excellent tracking and dE/dx performance. Timepix4 development is ongoing.
- During the test beam ~10⁶ events were successfully collected, all results showed that **a pixel TPC is realistic.**
- Ion back flow of the module has been measured and the analysis regular meeting were set up every month with IHEP and Bonn University.





DESY testbeam in June 2021

https://arxiv.org/abs/1902.01987 Huirong Oi

dN/dx cluster counting

- Challenging for the **low power consumption** electronics (>40mV/fC needed at 2000 of gas gain)
- Pixelated readout
 - \rightarrow high granularity readout in endplate
 - \rightarrow the reasonable pixilation reveals the underlying cluster structure in 3D chamber
- Occupancy of the pixelated TPC
 - Occupancy is very key issue at the high rate or high luminosity
 - Smaller pad/pixel size
 → smaller occupancy
 - To be addressed by R&D

 → A detailed simulation would
 be necessary to determine the
 scaling factor
 - \rightarrow Simulation ongoing at IHEP



High granularity for improved PID in TPC

- Current full ILD reconstruction: 6mm pads → ~4.8% dE/dx resolution
- 6mm \rightarrow 1mm: 15% improved resolution via the charge summation (dE/dx)
- 6mm \rightarrow 0.1mm: 30% improved resolution via the cluster counting (dN/dx)
 - Pad size of about 300µm can record ~1 primary cluster along track length at T2K gas
 - High **readout granularity** VS the primary cluster size optimization



All studies ongoing

Updated of the pixelated TPC R&D for CEPC at IHEP/Tsinghua

- **R&D on Macro-Pixel TPC readout for CEPC**
 - Macro-Pixel TPC ASIC chip was started to developed in this year and **1st prototype wafer has done in December**.
 - The first version ROIC has been received and under testing. Interposer PCB
 - The **TOA and TOT** can be selected as the initiation function in the ASIC chip.
 - $1 \text{mm} \times 6 \text{mm} \rightarrow 500 \mu \text{m} \times 500 \mu \text{m}$ pixel readout
 - Higher precision and higher rate (MHz/cm²)
 - Gain of the amplification: >40mV/fC
 - Channels: 128
 - Time resolution: 14bit (5ns bin)
 - Time discriminator: TOA (Time of Arrival)
 - Power consumption: <1mW/pixel (1st prototype)
 - $\sim 400 \text{mW/cm}^2$
 - 100mW/cm² (Goal and final design)
 - Technology: 180nm CMOS
 - High metal coverage: 4-side buttable



1st readout PCB board and the ASIC layout

- TPC tracking using GEM, Micromegas and GridPix pad and pixelated readouts have been developed for the future e+e- colliders.
- Analysis of test beam data with similar set of GEM, Micromegas and Gridpix modules demonstrated the proof-of-concept and validated these technologies.
- The TPC prototype integrated 266nm UV laser tracks has successfully developed at IHEP in the last few years, the results promised the spatial resolution and dE/dx. Macro-Pixel TPC ASIC chip was started to developed in this year and the tests will be starting.
- Synergies with CEPC/FCCee/EIC/T2K/ALICE allow us to continue R&D and ongoing, we learn from their experiences and R&D.

Many thanks!